











CD54HC4051, CD74HC4051 CD54HCT4051, CD74HCT4051, CD54HC4052, CD74HC4052, CD54HCT4052 CD74HCT4052, CD54HC4053, CD74HC4053, CD54HCT4053

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CDx4HC405x, CDx4HCT405x High-Speed CMOS Logic Analog **Multiplexers and Demultiplexers**

Features

- Wide Analog Input Voltage Range: ±5-V Maximum
- Low ON-Resistance
 - 70-Ω Typical (V_{CC} V_{EE} = 4.5 V)
 - 40- Ω Typical (V_{CC} V_{EE} = 9 V)
- Low Crosstalk Between Switches
- Fast Switching and Propagation Speeds
- Break-Before-Make Switching
- Wide Operating Temperature Range: -55°C to +125°C
- CD54HC and CD74HC Types
 - Operation Control Voltage: 2 V to 6 V
 - Switch Voltage: 0 V to 10 V
- CD54HCT and CD74HCT Types
 - Operation Control Voltage: 4.5 V to 5.5 V
 - Switch Voltage: 0 V to 10 V
 - Direct LSTTL Input Logic Compatibility $V_{IL} = 0.8-V \text{ Max}, V_{IH} = 2-V \text{ Min}$
 - CMOS Input Compatibility $I_1 \le 1 \,\mu\text{A} \text{ at } V_{OL}, V_{OH}$
- On Products Compliant to MIL-PRF-38535, All Parameters Are Tested Unless Otherwise Noted. On All Other Products, Production Processing Does Not Necessarily Include Testing of All Parameters.

2 Applications

- Digital Radio
- Signal Gating
- **Factory Automation**
- **Televisions**
- **Appliances**
- Programmable Logic Circuits
- Sensors

3 Description

The CDx4HC405x and CDx4HCT405x devices are digitally controlled analog switches that use silicon gate CMOS technology to achieve operating speeds similar to LSTTL with the low-power consumption of standard CMOS integrated circuits.

These analog multiplexers and demultiplexers control analog voltages that may vary across the voltage supply range (for example, V_{CC} to V_{EE}). They are bidirectional switches that allow any analog input to be used as an output and vice versa. The switches have low ON resistance and low OFF leakages. In addition, all these devices have an enable control that, when high, disables all switches to their OFF state.

Device Information⁽¹⁾

PART NUMBER	PACKAGE	BODY SIZE (NOM)
CD54HCx405xF	CDIP (16)	19.56 mm × 6.92 mm
CD74HCx405xE	PDIP (16)	19.30 mm × 6.35 mm
CD74HCx405xM	SOIC (16)	9.90 mm × 3.91 mm
CD74HCx405xNS	SOP (16)	10.30 mm × 5.30 mm
CD74HCx405xPW	TSSOP (16)	5.00 mm × 4.40 mm

(1) For all available packages, see the orderable addendum at the end of the data sheet.

Functional Diagram of HC4051 and HCT4051

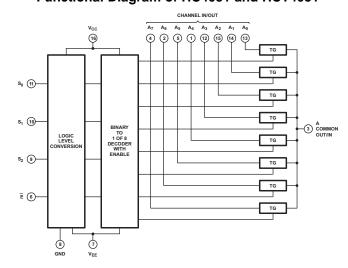




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4 Revision History

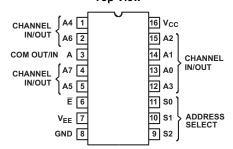
NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

Char	nges from Revision L (February 2017) to Revision M	age
• (Changed Feature From: 7-Ω Typical To: 70-Ω Typical	1
Char	nges from Revision K (September 2015) to Revision L	age
• 0	Changed Charged device model (CDM) value from: ±1000 V to: ±200 V	6
• A	dded Receiving Notification of Documentation Updates section	26
Char	nges from Revision J (February 2011) to Revision K	age
	demoved Ordering Information table.	_
• A	dded Device Information table, Pin Functions table, ESD Ratings table, Thermal Information table, Detailed	
	Description section, Applications and Implementation section, Power Supply Recommendations section, Layout ection, Device and Documentation Support section, and Mechanical, Packaging, and Orderable Information section	1
• A	dded Military Disclaimer to Features list.	1



5 Pin Configuration and Functions

CD54HC4051, CD54HCT4051, CD74HC4051, CD74HCT4051 J, N, D, NS, PW Packages 16-Pin CDIP, PDIP, SOIC, SO, TSSOP Top View

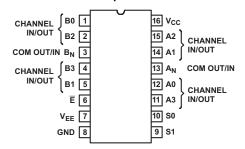


Pin Functions for CDx4HCx4051B

			Turiotiono for ODA-Front B			
PIN		I/O	DESCRIPTION			
NO.	NAME	1/0	DESCRIPTION			
1	CH A4 IN/OUT	I/O	Channel 4 in/out			
2	CH A6 IN/OUT	I/O	Channel 6 in/out			
3	COM OUT/IN	I/O	Common out/in			
4	CH A7 IN/OUT	I/O	Channel 7 in/out			
5	CH A5 IN/OUT	I/O	Channel 5 in/out			
6	Ē	I	Enable Channels (Active Low). See Table 1.			
7	V _{EE}	_	Negative power input			
8	GND	_	Ground			
9	S2	I	Channel select 2. See Table 1.			
10	S1	I	Channel select 1. See Table 1.			
11	S0	I	Channel select 0. See Table 1.			
12	CH A3 IN/OUT	I/O	Channel 3 in/out			
13	CH A0 IN/OUT	I/O	Channel 0 in/out			
14	CH A1 IN/OUT	I/O	Channel 1 in/out			
15	CH A2 IN/OUT	I/O	Channel 2 in/out			
16	V _{CC}	_	Positive power input			



CD54HC4052, CD74HC4052, CD74HCT4052 J, N, D, NS, PW Packages 16-Pin CDIP, PDIP, SOIC, SO, TSSOP Top View

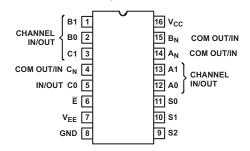


Pin Functions for CDx4HCx4052B

	PIN	1/0	DESCRIPTION
NO.	NAME	I/O	DESCRIPTION
1	CH B0 IN/OUT	I/O	Channel B0 in/out
2	CH B2 IN/OUT	I/O	Channel B2 in/out
3	COM B OUT/IN	I/O	B common out/in
4	CH B3 IN/OUT	I/O	Channel B3 in/out
5	CH B1 IN/OUT	I/O	Channel B1 in/out
6	Ē	I	Enable channels (Active Low). See Table 2.
7	V _{EE}		Negative power input
8	GND		Ground
9	S1	1	Channel select 1. See Table 2.
10	S0	I	Channel select 0. See Table 2.
11	CH A3 IN/OUT	I/O	Channel A3 in/out
12	CH A0 IN/OUT	I/O	Channel A0 in/out
13	COM A IN/OUT	I/O	A common out/in
14	CH A1 IN/OUT	I/O	Channel A1 in/out
15	CH A2 IN/OUT	I/O	Channel A2 in/out
16	V _{CC}	_	Positive power input



CD54HC4053 CD74HC4053 CD74HCT4053 J, N, D, NS, PW Packages 16-Pin CDIP, PDIP, SOIC, SOP, TSSOP TOP VIEW



Pin Functions CDx4HCx4053B

PIN		1/0	DECODINE
NO.	NAME	I/O	DESCRIPTION
1	B1 IN/OUT	I/O	B channel Y in/out
2	B0 IN/OUT	I/O	B channel X in/out
3	C1 IN/OUT	I/O	C channel Y in/out
4	COM C OUT/IN	I/O	C common out/in
5	C0 IN/OUT	I/O	C channel X in/out
6	Ē	ı	Enable channels (Active Low). See Table 3.
7	V _{EE}	_	Negative power input
8	GND	_	Ground
9	S2	ı	Channel select 2. See Table 3.
10	S1	I	Channel select 1. See Table 3.
11	S0	I	Channel select 0. See Table 3.
12	A0 IN/OUT	I/O	A channel X in/out
13	A1 IN/OUT	I/O	A channel Y in/out
14	COM A OUT/IN	I/O	A common out/in
15	COM B OUT/IN	I/O	B common out/in
16	V _{CC}	_	Positive power input



6 Specifications

6.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)⁽¹⁾

			MIN	MAX	UNIT	
V _{CC} - V _{EE}	DC supply voltage		-0.5	10.5	V	
V _{CC}	DC supply voltage	-0.5	7	V		
V _{EE}	DC supply voltage	DC supply voltage				
I _{IK}	DC input diode current	$V_{I} < -0.5 \text{ V or } V_{I} > V_{CC} + 0.5 \text{ V}$		±20	mA	
I _{OK}	DC switch diode current	$V_I < V_{EE} - 0.5 \text{ V or } V_I > V_{CC} + 0.5 \text{ V}$		±20	mA	
	DC switch current ⁽²⁾	$V_{I} > V_{EE} - 0.5 \text{ V or } V_{I} < V_{CC} + 0.5 \text{ V}$		±25	mA	
I _{CC}	DC V _{CC} or ground current			±50	mA	
I _{EE}	DC V _{EE} current			-20	mA	
T _{JMAX}	Maximum junction temperature			150	°C	
T _{LMAX}	Maximum lead temperature	Soldering 10 s		300	°C	
TJ	Junction temperature			150	°C	
T _{stg}	Storage temperature		-65	150	°C	

⁽¹⁾ Stresses beyond those listed under Absolute Maximum Ratings may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under Recommended Operating Conditions is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

6.2 ESD Ratings

			VALUE	UNIT
		Human body model (HBM), per ANSI/ESDA/JEDEC JS-001 (1)	±500	
	V _(ESD) Electrostatic discharge	Charged device model (CDM), per JEDEC specification JESD22-C101 or ANSI/ESDA/JEDEC JS-002 (2)	±200	V

⁽¹⁾ JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.

6.3 Recommended Operating Conditions

over operating free-air temperature range (unless otherwise noted)⁽¹⁾

			MIN	NOM MAX	UNIT
	Supply voltage range	CD54 and 74HC types	2	6	
V _{CC}	(T _A = full package temperature range) ⁽²⁾	CD54 and 74HCT types	4.5	5.5	V
V _{CC} – V _{EE}	Supply voltage range (T _A = full package temperature range)	CD54 and 74HC types, CD54 and 74HCT types (see Figure 1)	2	10	V
V _{EE}	Supply voltage range (T _A = full package temperature range) ⁽³⁾	CD54 and 74HC types, CD54 and 74HCT types (see Figure 2)	0	-6	V
VI	DC input control voltage		GND	V _{CC}	V
V _{IS}	Analog switch I/O voltage		V _{EE}	V _{CC}	V
T _A	Operating temperature		– 55	125	°C
		2 V	0	1000	
t _r , t _f	Input rise and fall times	4.5 V	0	500	ns
		6 V	0	2 6 4.5 5.5 2 10 0 -6 GND V _{CC} V _{EE} V _{CC} -55 125 0 1000 0 500	

⁽¹⁾ For maximum reliability, nominal operating conditions must be selected so that operation is always within the ranges specified in the Recommended Operating Conditions table.

⁽²⁾ All voltages referenced to GND unless otherwise specified.

⁽²⁾ JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.

⁽²⁾ All voltages referenced to GND unless otherwise specified.

⁽³⁾ In certain applications, the external load resistor current may include both V_{CC} and signal line components. To avoid drawing V_{CC} current when switch current flows into the transmission gate inputs, the voltage drop across the bidirectional switch must not exceed 0.6 V (calculated from r_{ON} values shown in *Electrical Characteristics: HC Devices* and *Electrical Characteristics: HCT Devices* tables). No V_{CC} current will flow through R_L if the switch current flows into terminal 3 on the HC and HCT4051; terminals 3 and 13 on the HC and HCT4052; terminals 4, 14, and 15 on the HC and HCT4053.



6.4 Thermal Information

			CD74HC4051				
	THERMAL METRIC ⁽¹⁾	N (PDIP)	NS (SO)	PW (TSSOP)	UNIT		
		16 PINS	16 PINS	16 PINS			
$R_{\theta JA}$	Junction-to-ambient thermal resistance	49.0	83.0	107.7	°C/W		
$R_{\theta JC(top)}$	Junction-to-case (top) thermal resistance	36.3	41.2	42.4	°C/W		
$R_{\theta JB}$	Junction-to-board thermal resistance	29.0	43.3	52.8	°C/W		
ΨЈТ	Junction-to-top characterization parameter	21.2	9.2	4.2	°C/W		
ΨЈВ	Junction-to-board characterization parameter	28.9	43.0	52.2	°C/W		

⁽¹⁾ For more information about traditional and new thermal metrics, see the Semiconductor and IC Package Thermal Metrics application report.

6.5 Electrical Characteristics: HC Devices

			TEST C	ONDITIONS						
	PARAMETERS	V _{IS} (V)	V _I (V)	V _{EE} (V)	V _{cc} (V)	T _A	MIN	TYP	MAX	UNIT
						25°C	1.5			
					2	–40°C to +85°C	1.5			
						–55°C to +125°C	1.5			
						25°C	3.15			
V _{IH}	High-level input voltage				4.5	–40°C to +85°C	3.15			V
						–55°C to +125°C	3.15			
					6	25°C	4.2			
						–40°C to +85°C	4.2			
						–55°C to +125°C	4.2			
					2	25°C			0.5	
						-40°C to +85°C			0.5	
						–55°C to +125°C			0.5	
						25°C			1.35	
V _{IL}	Low-level input voltage				4.5	–40°C to +85°C			1.35	V
						–55°C to +125°C			1.35	
						25°C			1.8	
					6	–40°C to +85°C			1.8	
						–55°C to +125°C			1.8	



Electrical Characteristics: HC Devices (continued)

				TEST CONDITIONS																		
	PARAMET	TERS	V _{IS} (V)	V ₁ (V)	V _{EE} (V)	V _{cc} (V)	T _A	MIN	TYP	MAX	UNIT											
										25°C		70	160									
							0	0 4.5	-40°C to +85°C			200										
							–55°C to +125°C			240												
							25°C		60	140												
			V _{CC} or V _{EE}		0	6	-40°C to +85°C			175												
							−55°C to +125°C			210												
	ON resistance						25°C		40	120												
		I _O = 1 mA See Figure 21		V _{IL}		-4.5	-4.5 4.5	-40°C to +85°C			150											
							−55°C to +125°C			180	Ω											
r _{ON}			See Figure 21	See Figure 21	21	or V _{IH}			25°C		90	180	22									
							0	4.5	-40°C to +85°C			225										
							–55°C to +125°C			270												
							25°C		80	160												
				İ	İ							ı	ı	V _{CC} to V _{EE}		0	6	-40°C to +85°C			200	
							–55°C to +125°C			240												
							25°C		45	130												
						-4.5	4.5	-40°C to +85°C			162											
				−55°C to +125°C			195															
					0	4.5	25°C		10													
Δr_{ON}	Maximum ON between any				0	6	25°C	·	8.5		Ω											
		-			-4.5	4.5	25°C		5													



Electrical Characteristics: HC Devices (continued)

				TEST C	ONDITIONS																		
	PARAMET	TERS	V _{IS} (V)	V ₁ (V)	V _{EE} (V)	V _{CC} (V)	T _A	MIN TYP MAX	UNIT														
							25°C	±0.1															
		1 and 2 channels			0	6	-40°C to +85°C	±1															
							−55°C to +125°C	±1															
							25°C	±0.1															
		4053			-5	5	-40°C to +85°C	±1															
							–55°C to +125°C	±1															
							25°C	±0.1															
		4 channels	For switch OFF: When V _{IS} = V _{CC} ,		0	6	-40°C to +85°C	±1															
	Switch ON/OFF		V _{IL}			–55°C to +125°C	±1	μA															
I _{IZ}	leakage current		For switch ON: All applicable	V _{IH}			25°C	±0.2	μΑ														
	current	4052 All applicable combinations of V _{IS} and V _{OS} voltage levels		-5	5	–40°C to +85°C	±2																
			voltage levels				−55°C to +125°C	±2															
							25°C	±0.2															
		8 channels			0	6	-40°C to +85°C	±2															
							–55°C to +125°C	±2															
																					25°C	±0.4	
		4051									- 5	5	-40°C to +85°C	±4									
							–55°C to +125°C	±4															
							25°C	±0.1															
I _{IL}	Control input	leakage current		V _{CC} or	0	6	–40°C to +85°C	±1	μΑ														
				GND			–55°C to +125°C	±1															
							25°C	8															
			When $V_{IS} = V_{EE}$, $V_{OS} = V_{CC}$		0	6	-40°C to +85°C	80															
	Quiescent		-03 -00	V _{CC}			−55°C to +125°C	160															
I _{CC}	device current	I _O = 0		or GND			25°C	16	μΑ														
	outon		When $V_{IS} = V_{CC}$, $V_{OS} = V_{EE}$		- 5	5	-40°C to +85°C	160)														
			-03 •EE				−55°C to +125°C	320															



6.6 Electrical Characteristics: HCT Devices

				TEST C	ONDITIONS	3						
	PARAMETI	ER	V _{IS} (V)	V ₁ (V)	V _{EE} (V)	V _{cc} (V)	T _A	MIN	TYP	MAX	UNIT	
							25°C	2				
V _{IH}	V _{IH} High-level input voltage				4.5 to 5.5	-40°C to +85°C	2			V		
						5.5	-55°C to +125°C	2				
							25°C			0.8		
V _{IL}	Low-level input	voltage				4.5 to	-40°C to +85°C			0.8	V	
						5.5	-55°C to +125°C			0.8		
							25°C		70	160		
					0	4.5	-40°C to +85°C			200		
							-55°C to +125°C			240		
			V _{CC} or V _{EE}				25°C		40	120		
					-4.5	4.5	-40°C to +85°C			150		
		I _O = 1 mA		V _{IL}			-55°C to +125°C			180	_	
r _{ON}	ON resistance	See Figure 6		or V _{IH}			25°C		90	180	Ω	
		" 0		""	- in	0	4.5	-40°C to +85°C			225	
			, , , , , ,				-55°C to +125°C			270		
			V _{CC} to V _{EE}				25°C		45	130		
					-4.5	4.5	-40°C to +85°C			162		
							-55°C to +125°C			195		
۸r	Maximum ON r				0	4.5	25°C		10		Ω	
Δr_{ON}	between any tv	vo channels			-4.5	4.5	25°C		5		2.2	





Electrical Characteristics: HCT Devices (continued)

				TEST C	NOITION	S				
	PARAMET	ER	V _{IS} (V)	V ₁ (V)	V _{EE} (V)	V _{CC} (V)	TA	MIN TYP I	MAX	UNIT
							25°C		±0.1	
		1 and 2 channels			0	6	-40°C to +85°C		±1	
							−55°C to +125°C		±1	
							25°C		±0.1	
		4053			– 5	5	-40°C to +85°C		±1	
							−55°C to +125°C		±1	
							25°C		±0.1	
		0	6	-40°C to +85°C		±1				
	Switch ON/OFF				−55°C to +125°C		±1			
I _{IZ}	leakage		For switch ON:	or V _{IH}			25°C		±0.2	μΑ
	current	4052	All applicable combinations of V _{IS} and V _{OS}		- 5	5	-40°C to +85°C		±2	
			voltage levels				−55°C to +125°C		±2	
					0		25°C		±0.2	
		8 channels				6	-40°C to +85°C		±2	
					−55°C to +125°C		±2			
							25°C		±0.4	
		4051			- 5	5	-40°C to +85°C		±4	
							−55°C to +125°C		±4	
							25°C		±0.1	
I _{IL}	Control input le	eakage current		See ⁽¹⁾		5.5	-40°C to +85°C		±1	μΑ
							–55°C to +125°C		±1	
							25°C		8	
			When $V_{IS} = V_{EE}$, $V_{OS} = V_{CC}$		0	5.5	-40°C to +85°C		80	μΑ
	Quiescent		- US - * UC	V _{CC}			−55°C to +125°C		160	
I _{CC}	device current	$I_{O} = 0$		or GND			25°C		16	
		When $V_{IS} = V_{CC}$, $V_{OS} = V_{EE}$	-4.5	5.5	-40°C to +85°C		160	μA		
			*US = *EE				−55°C to +125°C		320	
							25°C	100	360	
ΔI_{CC}	Additional quie		$\Delta I_{CC}^{(2)}$	V _{CC} - 2.1		4.5 to 5.5	-40°C to +85°C		450	μΑ
	1 unit load ⁽²⁾						−55°C to +125°C		490	

Any voltage between V_{CC} and GND. For dual-supply systems, theoretical worst-case (V_I = 2.4 V, V_{CC} = 5.5 V) specification is 1.8 mA.



6.7 Switching Characteristics, $V_{CC} = 5 \text{ V}$

 $V_{CC} = 5 \text{ V}, T_A = 25^{\circ}\text{C}, \text{ input } t_r, t_f = 6 \text{ ns}$

	PARAMETER	TEST CO	NDITIONS	C _L (pF)	MIN TYP MAX	UNIT	
			CDx4HC4051		4		
			CDx4HCT4051		4		
		Switch IN to OUT	CDx4HC4052	1	4		
t _{PHL} , t _{PLH}			CDx4HCT4052	15	4	ns	
			CDx4HC4053		4		
			CDx4HCT4053		4		
			CDx4HC4051		19		
			CDx4HCT4051		19		
	Propagation delay		0 % L & # (0 E)	CDx4HC4052	1 [21	
$_{PHZ},t_{PLZ}$		Switch turn-off (S or \overline{E})	CDx4HCT4052	15	21	ns	
			CDx4HC4053		18	Ī	
			CDx4HCT4053		18		
			CDx4HC4051		19		
			CDx4HCT4051		23	ns	
		0 - itali tama an (0 -	CDx4HC4052	4.5	27		
PZH, tPZL		Switch turn-on (S or \overline{E})	CDx4HCT4052	15	29		
			CDx4HC4053		18		
			CDx4HCT4053		20		
	•		CDx4HC4051		50		
			CDx4HCT4051		52		
	Power dissipation		CDx4HC4052		74		
PD	capacitance ⁽¹⁾		CDx4HCT4052	1	76	pF	
			CDx4HC4053		38		
			CDx4HCT4053	1	42	Ť	

⁽¹⁾ C_{PD} is used to determine the dynamic power consumption, per package. $P_D = C_{PD} \ V_{CC}^2 \ f_I + \sum (C_L + C_S) \ V_{CC}^2 \ f_O$, $f_O =$ output frequency, $f_I =$ input frequency, $C_L =$ output load capacitance, $C_S =$ switch capacitance, $V_{CC} =$ supply voltage





6.8 Switching Characteristics, $C_L = 50 pF$

 $C_L = 50 \text{ pF}$, input t_r , $t_f = 6 \text{ ns}$

	PARAMETER		V _{EE} (V)	V _{CC} (V)	TEST CON	DITIONS	MIN MAX	UNIT
					T _A = 25°C	HC	60	
			0	2	$T_A = -40^{\circ}\text{C to } +85^{\circ}\text{C}$	HC	75	
					$T_A = -55^{\circ}C \text{ to } +125^{\circ}C$	HC	90	
		Ī			T _A = 25°C	HC, HCT	12	
			0	4.5	$T_A = -40^{\circ}C \text{ to } +85^{\circ}C$	HC, HCT	15	
PLH,	Propagation dela	av.			$T_A = -55^{\circ}C \text{ to } +125^{\circ}C$	HC, HCT	18	
PHL	switch in to out	,			T _A = 25°C	HC	10	ns
			0	6	$T_A = -40^{\circ}C \text{ to } +85^{\circ}C$	HC	13	
					$T_A = -55^{\circ}C \text{ to } +125^{\circ}C$	HC	15	
		Ī			T _A = 25°C	HC, HCT	8	
			-4.5	4.5	$T_A = -40^{\circ}\text{C} \text{ to } +85^{\circ}\text{C}$	HC, HCT	10	
					$T_A = -55^{\circ}C \text{ to } +125^{\circ}C$	HC, HCT	12	
					T _A = 25°C	HC	225	
			0	2	$T_A = -40^{\circ}C \text{ to } +85^{\circ}C$	HC	280	
					$T_A = -55^{\circ}C \text{ to } +125^{\circ}C$	HC	340	
		-			T _A = 25°C	HC, HCT	45	
	Maximum		0	4.5	$T_A = -40^{\circ}C \text{ to } +85^{\circ}C$	HC, HCT	56	nc
PHZ,	switch turn	1051			$T_A = -55^{\circ}C \text{ to } +125^{\circ}C$	HC, HCT	68	
PLZ	OFF delay from S or E	4051			T _A = 25°C	HC	38	ns
	to switch output		0	6	$T_A = -40^{\circ}C \text{ to } +85^{\circ}C$	HC	48	
					$T_A = -55^{\circ}C \text{ to } +125^{\circ}C$	HC	57	
		-		4.5	T _A = 25°C	HC, HCT	32	
			-4.5		$T_A = -40^{\circ}C \text{ to } +85^{\circ}C$	HC, HCT	40	
					$T_A = -55^{\circ}C \text{ to } +125^{\circ}C$	HC, HCT	48	
					T _A = 25°C	HC	250	
			0	2	$T_A = -40^{\circ}\text{C} \text{ to } +85^{\circ}\text{C}$	HC	315	
					$T_A = -55^{\circ}C \text{ to } +125^{\circ}C$	HC	375	
					T _A = 25°C	HC, HCT	50	
			0	4.5	$T_A = -40^{\circ}C \text{ to } +85^{\circ}C$	HC, HCT	63	
					$T_A = -55^{\circ}C \text{ to } +125^{\circ}C$	HC, HCT	75	
	Maximum switch turn	-			T _A = 25°C	HC	43	
PHZ,	OFF delay_	4052	0	6	$T_A = -40^{\circ}C \text{ to } +85^{\circ}C$	HC	54	ns
PLZ	from S or E to switch output				$T_A = -55^{\circ}C \text{ to } +125^{\circ}C$	HC	65	
	to Switch output					HC	38	
					T _A = 25°C	HCT	38	
				4.5	T 4000 : 0500	HC	48	
			-4.5	4.5	$T_A = -40$ °C to +85°C	HCT	48	8
					T 5500 to 140500	HC	57	
					$T_A = -55^{\circ}C \text{ to } +125^{\circ}C$	HCT	57	



Switching Characteristics, $C_L = 50 pF$ (continued)

 $C_L = 50 \text{ pF}$, input t_r , $t_f = 6 \text{ ns}$

PARAMETER		V _{EE} (V)	V _{CC} (V)	TEST CONI	DITIONS	MIN MAX	UNIT	
					T _A = 25°C	HC	210	
			0	2	$T_A = -40^{\circ}C \text{ to } +85^{\circ}C$	HC	265	
					$T_A = -55^{\circ}C \text{ to } +125^{\circ}C$	HC	315	
					T 25°C	HC	42	
					T _A = 25°C	HCT	44	
			0	4.5	$T_A = -40^{\circ}\text{C to } +85^{\circ}\text{C}$	HC	53	
			U	4.5	1 _A = -40 C to +65 C	HCT	53	
	Maximum				$T_A = -55^{\circ}\text{C to } +125^{\circ}\text{C}$	HC	63	
t _{PHZ} ,	switch turn	4053			T _A = -55 C to +125 C	HCT	66	ns
t _{PLZ}	OFF delay from S or E	4000			T _A = 25°C	HC	36	115
	to switch output		0	6	$T_A = -40^{\circ}C \text{ to } +85^{\circ}C$	HC	45	
					$T_A = -55^{\circ}C \text{ to } +125^{\circ}C$	HC	54	
					T 25%C	HC	29	
					T _A = 25°C	HCT	31	
			4.5	-4.5 4.5	4.5 $T_A = -40^{\circ}\text{C to } +85^{\circ}\text{C}$	HC	36	
			-4.5			HCT	39	
					$T_A = -55^{\circ}C \text{ to } +125^{\circ}C$	HC	44	
					1 _A = -55°C 10 +125°C	HCT	47	
				2	T _A = 25°C	HC	225	
			0		$T_A = -40$ °C to +85°C	HC	280	
					$T_A = -55^{\circ}C \text{ to } +125^{\circ}C$	HC	340	
					T 25%C	HC	45	
					T _A = 25°C	HCT	55	
			0	4.5	$T_A = -40^{\circ}\text{C to } +85^{\circ}\text{C}$	HC	56	
			U	4.5	1 _A = -40°C to +85°C	HCT	69	
	Maximum				T 5500 to 140500	HC	68	
t _{PZL} ,	switch turn	4054			$T_A = -55^{\circ}C \text{ to } +125^{\circ}C$	HCT	83	
t _{PZH}	ON delay from S or E	4051			T _A = 25°C	HC	38	ns
	to switch output		0	6	$T_A = -40$ °C to +85°C	HC	48	
					$T_A = -55^{\circ}C \text{ to } +125^{\circ}C$	HC	57	
				-4.5 4.5	T 25%C	HC	32	
					T _A = 25°C	HCT	39	
			4.5		T 40°C to 105°C	HC	40	
			-4.5		$T_A = -40$ °C to +85°C	HCT	49	
					T 5500 t 10500	HC	48	
					$T_A = -55^{\circ}C \text{ to } +125^{\circ}C$	HCT	59	



Switching Characteristics, $C_L = 50 pF$ (continued)

 $C_L = 50 \text{ pF}$, input t_r , $t_f = 6 \text{ ns}$

	PARAMETER		V _{EE} (V)	V _{cc} (V)	TEST CON	DITIONS	MIN MAX	UNIT	
					T _A = 25°C	HC	325		
			0	2	$T_A = -40^{\circ}\text{C to } +85^{\circ}\text{C}$	HC	405		
					$T_A = -55^{\circ}C \text{ to } +125^{\circ}C$	HC	490		
					T _A = 25°C	HC	65		
						HCT	70		
			0	4.5	$T_A = -40^{\circ}\text{C to } +85^{\circ}\text{C}$	HC	81		
			0	4.5		HCT	68		
	Maximum				T 5500 : 40500	HC	98		
t_{PZL} ,	switch turn	40.50			$T_A = -55^{\circ}C \text{ to } +125^{\circ}C$	HCT	105		
t _{PZH}	ON delay _ from S or E	4052			T _A = 25°C	HC	55	ns	
	to switch output		0	6	$T_A = -40^{\circ}\text{C to } +85^{\circ}\text{C}$	HC	69		
					$T_A = -55^{\circ}C \text{ to } +125^{\circ}C$	HC	83		
						НС	46		
					T _A = 25°C	HCT	48		
						НС	58		
			-4.5	4.5	$T_A = -40$ °C to +85°C	HCT	60		
						T. = _55°C to ±125°C	НС	69	
					$T_A = -55^{\circ}C \text{ to } +125^{\circ}C$	HCT	72		
						T _A = 25°C	НС	220	
			0	2	$T_A = -40^{\circ}\text{C to } +85^{\circ}\text{C}$	НС	275		
					$T_A = -55^{\circ}C \text{ to } +125^{\circ}C$	НС	330		
					T _A = 25°C	НС	44		
						HCT	48		
						НС	55		
			0	4.5	$T_A = -40^{\circ}C \text{ to } +85^{\circ}C$	HCT	60		
	Maximum					НС	66		
t _{PZL} ,	switch turn				$T_A = -55^{\circ}C \text{ to } +125^{\circ}C$	HCT	72		
t _{PZH}	ON delay from S or E	4053			T _A = 25°C	НС	37	ns	
	to switch output		0	6	$T_A = -40^{\circ}\text{C to } +85^{\circ}\text{C}$	НС	47		
					$T_A = -55^{\circ}\text{C to } +125^{\circ}\text{C}$	НС	56		
						НС	31		
					$T_A = 25^{\circ}C$	HCT	34		
						НС	39		
		-4.5 4.5	4.5	$T_A = -40^{\circ}C \text{ to } +85^{\circ}C$	HCT	43			
						HC	47		
					$T_A = -55^{\circ}C \text{ to } +125^{\circ}C$	HCT	51		
					T _A = 25°C	HC, HCT	10		
Cı	Input (control)				$T_A = -40^{\circ}\text{C to } +85^{\circ}\text{C}$	HC, HCT	10	pF	
	capacitance				$T_A = -55^{\circ}\text{C to } +125^{\circ}\text{C}$	HC, HCT	10	•	



6.9 Analog Channel Specifications

Typical values at T_A = 25°C

	PARAMETER	TEST CONDITIONS	HC, HCT TYPES	V _{EE} (V)	V _{CC} (V)	TYP	UNIT	
C _I	Switch input capacitance		All			5	pF	
			4051			25		
C _{COM}	Common output capacitance		4052			12	pF	
			4053			8		
			4051			145		
	Minimum switch frequency		4052	-2.25	2.25	165	MHz	
f	response at –3 dB	See Figure 10 ⁽¹⁾⁽²⁾	4053			200		
'MAX	(see Figure 3, Figure 5, and		4051	-4.5		180		
	Figure 7)		4052		4.5	185		
			4053			200		
	Sine-wave distortion	Soo Figure 12	All	-2.25%	2.25%	0.035%		
	Sine-wave distortion	See Figure 12	All	-4.5%	4.5%	0.018%		
			4051	-2.25	2.25	-73		
	Switch OFF signal feedthrough (see Figure 4, Figure 6, and Figure 8)		4052			-65		
		See Figure 14 ⁽²⁾⁽³⁾	4053			-64	٩D	
		See rigure 14(-/\frac{1}{2})	4051	-4.5	4.5	-75	dB	
			4052			-67		
			4053			-66		

Adjust input voltage to obtain 0 dBm at V_{OS} for $f_{IN} = 1$ MHz.

 $V_{\rm IS}$ is centered at ($V_{\rm CC} - V_{\rm EE}$) / 2. Adjust input for 0 dBm.

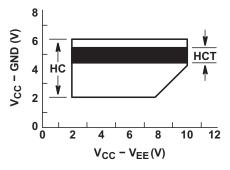


Figure 1. Recommended Operating Area as a Function of (V_{CC} - V_{EE})

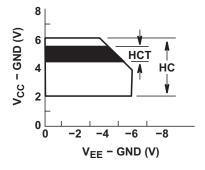
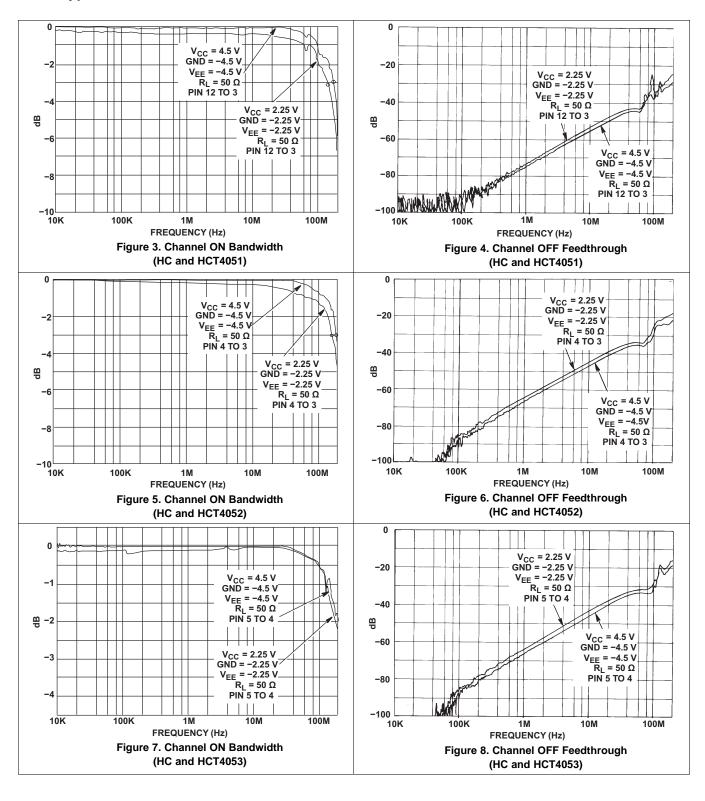


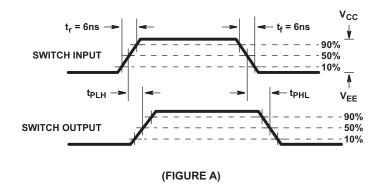
Figure 2. Recommended Operating Area as a Function of (V_{EE} – GND)

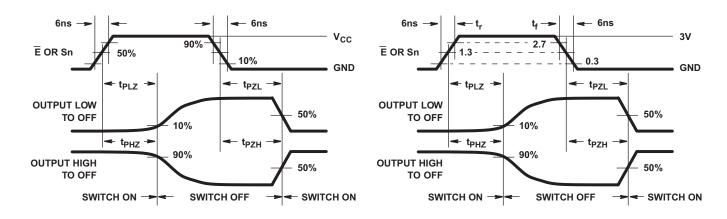


6.10 Typical Characteristics



7 Parameter Measurement Information





(FIGURE B) HC TYPES

(FIGURE C) HCT TYPES

Figure 9. Switch Propagation Delay, Turn-On, Turn-Off Times

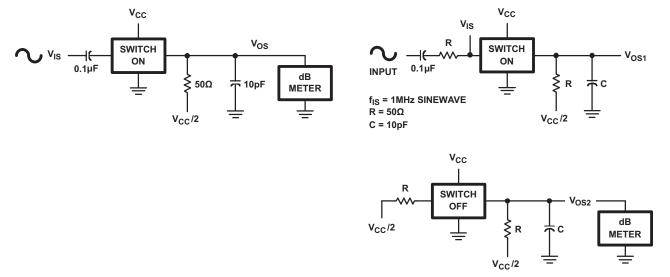


Figure 10. Frequency Response Test Circuit

Figure 11. Crosstalk Between Two Switches
Test Circuit



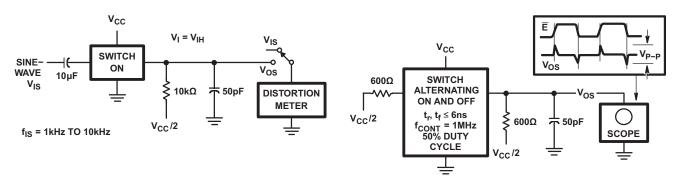


Figure 12. ¼Sine-Wave Distortion Test Circuit

Figure 13. Control to Switch Feedthrough Noise Test Circuit

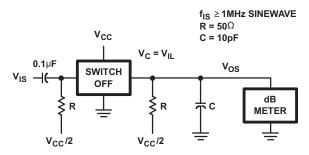


Figure 14. Switch OFF Signal Feedthrough

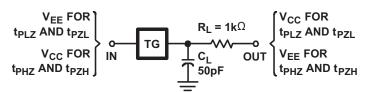


Figure 15. Switch ON/OFF Propagation Delay Test Circuit

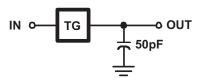


Figure 16. Switch In to Switch Out Propagation Delay Test Circuit



8 Detailed Description

8.1 Overview

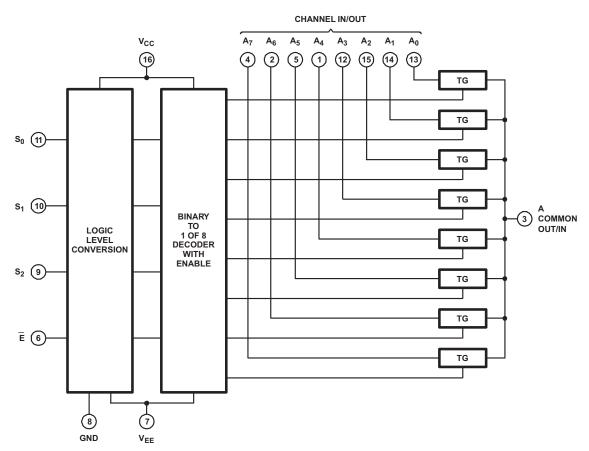
The CDx4HCx4051 devices are a single 8-channel multiplexer having three binary control inputs, S_0 , S_1 , and S_2 and an ENABLE input. The three binary signals select 1 of 8 channels to be turned on, and connect one of the 8 inputs to the output.

The CDx4HCx4052 devices are a differential 4-channel multiplexer having two binary control inputs, S_0 and S_1 , and an ENABLE input. The two binary input signals select 1 of 4 pairs of channels to be turned on and connect the analog inputs to the outputs.

The CDx4HCx4053 devices are a triple 2-channel multiplexer having three separate digital control inputs, S_0 , S_1 , and S_2 and an ENABLE input. Each control input selects one of a pair of channels that are connected in a single-pole, double-throw configuration.

When these devices are used as demultiplexers, the CHANNEL IN/OUT terminals are the outputs and the COMMON OUT/IN terminals are the inputs.

8.2 Functional Block Diagrams

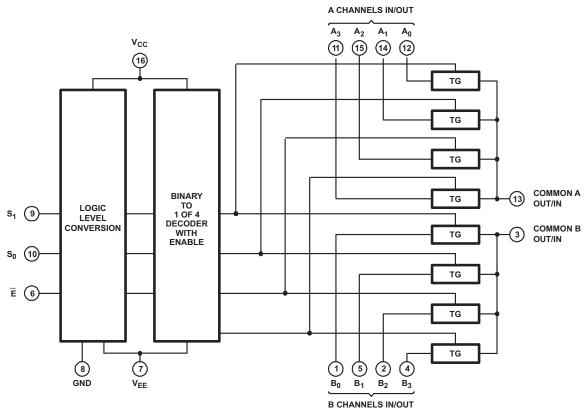


All inputs are protected by standard CMOS protection network.

Figure 17. CDx4HCx4051 Functional Block Diagram

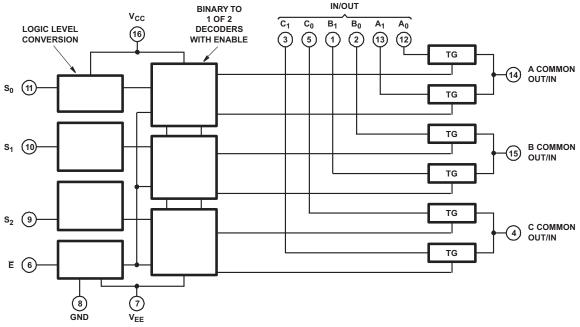


Functional Block Diagrams (continued)



All inputs are protected by standard CMOS protection network.

Figure 18. CDx4HCx4052 Functional Block Diagram



All inputs are protected by standard CMOS protection network.

Figure 19. CDx4HCx4053 Functional Block Diagram



8.3 Feature Description

The CDx4HCx405x line of multiplexers and demultiplexers can accept a wide range of analog signal levels from -5 to +5 V. They have low ON resistance, typically $70-\Omega$ for $V_{CC}-V_{EE}=4.5$ V and $40-\Omega$ for $V_{C}-V_{EE}=4.5$ V, which allows for very little signal loss through the switch.

Binary address decoding on chip makes channel selection easy. When channels are changed, a break-before-make system eliminates channel overlap.

8.4 Device Functional Modes

Table 1. CD54HC4051, CD74HC4051, CD54HCT4051, CD74HCT4051 Function Table (1)

	INPUT STATES									
ENABLE	S ₂	S ₁	S ₀	CHANNEL						
L	L	L	L	A0						
L	L	L	Н	A1						
L	L	Н	L	A2						
L	L	Н	Н	A3						
L	Н	L	L	A4						
L	Н	L	Н	A5						
L	Н	Н	L	A6						
L	Н	Н	Н	A7						
Н	X	X	Х	None						

⁽¹⁾ X = Don't care

Table 2. CD54HC4052, CD74HC4052, CD54HCT4052, CD74HCT4052 Function Table (1)

	INPUT STATES								
ENABLE	S ₁	S ₀	CHANNELS						
L	L	L	A0, B0						
L	L	Н	A1, B1						
L	Н	L	A2, B2						
L	Н	Н	A3, B3						
Н	X	X	None						

⁽¹⁾ X = Don't care

Table 3. CD54HC4053, CD74HC4053, CD54HCT4053, CD74HCT4053 Function Table (1)

	INPUT STATES									
ENABLE	S ₂	S ₁	S ₀	CHANNELS						
L	L	L	L	C0, B0, A0						
L	L	L	Н	C0, B0, A1						
L	L	Н	L	C0, B1, A0						
L	L	Н	Н	C0, B1, A1						
L	Н	L	L	C1, B0, A0						
L	Н	L	Н	C1, B0, A1						
L	Н	Н	L	C1, B1, A0						
L	Н	Н	Н	C1, B1, A1						
Н	Х	X	X	None						

⁽¹⁾ X = Don't care



9 Application and Implementation

NOTE

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes. Customers should validate and test their design implementation to confirm system functionality.

9.1 Application Information

The CDx4HCx405x line of multiplexers and demultiplexers can be used for a wide variety of applications.

9.2 Typical Application

One application of the CD74HC4051 device is used in conjunction with a microcontroller to poll a keypad. Figure 20 shows the basic schematic for such a polling system. The microcontroller uses the channel-select pins to cycle through the different channels while reading the input to see if a user is pressing any of the keys. This is a very robust setup that allows for simultaneous key presses with very little power consumption. It also uses very few pins on the microcontroller. The down side of polling is that the microcontroller must frequently scan the keys for a press.

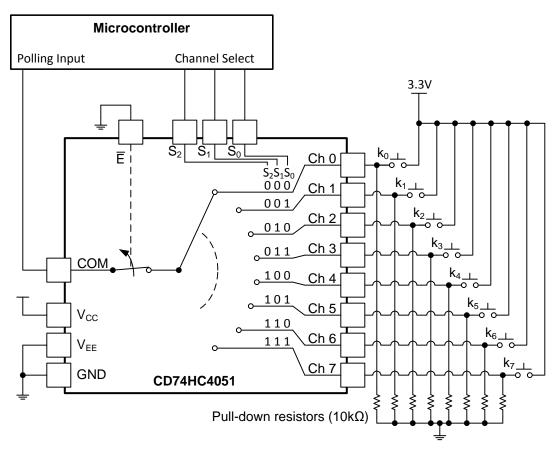


Figure 20. CD74HC4051 Being Used to Help Read Button Presses on a Keypad

9.2.1 Design Requirements

These devices use CMOS technology and have balanced output drive. Take care to avoid bus contention because it can drive currents that would exceed maximum limits. The high drive will also create fast edges into light loads, so routing and load conditions must be considered to prevent ringing.

Typical Application (continued)

See Table 4 for the input loading details.

Table 4. HCT Input Loading Table

TYPE	INPUT	UNIT LOADS ⁽¹⁾
4051, 4053	All	0.5
4052	All	0.4

(1) Unit load is ∆I_{CC} limit specified in *Specifications*, for example, 360-mA MAX at 25°C.

9.2.2 Detailed Design Procedure

- 1. Recommended input conditions:
 - For switch time specifications, see propagation delay times in *Electrical Characteristics: HC Devices*.
 - Inputs must not be pushed more than 0.5 V above V_{DD} or below V_{EE}.
 - For input voltage level specifications for control inputs, see V_{IH} and V_{IL} in *Electrical Characteristics: HC Devices*.
- 2. Recommended output conditions:
 - Outputs must not be pulled above V_{DD} or below V_{EE}.
- 3. Input and output current consideration:
 - The CDx4HCx405x series of parts do not have internal current-drive circuitry, and thus cannot sink or source current. Any current will be passed through the device.

9.2.3 Application Curve

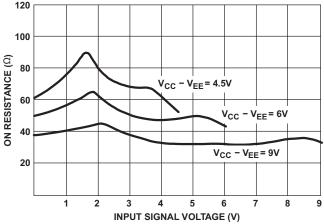


Figure 21. Typical ON Resistance vs Input Signal Voltage

10 Power Supply Recommendations

The power supply can be any voltage between the minimum and maximum supply voltage rating located in the *Electrical Characteristics: HC Devices*.

Each V_{CC} terminal must have a good bypass capacitor to prevent power disturbance. For devices with a single supply, a 0.1- μF bypass capacitor is recommended. If there are multiple pins labeled V_{CC} , then a 0.01- μF or 0.022- μF capacitor is recommended for each V_{CC} because the V_{CC} pins will be tied together internally. For devices with dual-supply pins operating at different voltages, for example V_{CC} and V_{DD} , a 0.1- μF bypass capacitor is recommended for each supply pin. It is acceptable to parallel multiple bypass capacitors to reject different frequencies of noise. A 0.1- μF and a 1- μF capacitor are commonly used in parallel. For best results, the bypass capacitor or capacitors must be installed as close as possible to the power terminal.



11 Layout

11.1 Layout Guidelines

Reflections and matching are closely related to loop antenna theory, but different enough to warrant their own discussion. When a PCB trace turns a corner at a 90° angle, a reflection can occur. This is primarily due to the change in width of the trace. At the apex of the turn, the trace width is increased to 1.414 times its width. This change in width upsets the transmission line characteristics, especially the distributed capacitance and self-inductance of the trace, thus resulting in the reflection. Not all PCB traces can be straight, so they will have to turn corners. Figure 22 shows progressively better techniques of rounding corners. Only the last example (BEST) maintains constant trace width and minimizes reflections.

11.2 Layout Example

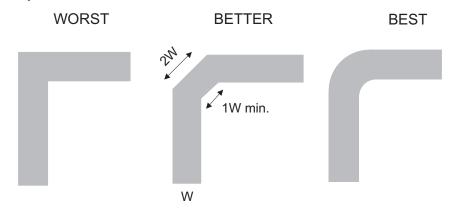


Figure 22. Trace Example



12 Device and Documentation Support

12.1 Documentation Support

12.1.1 Related Documentation

For related documentation see the following: Implications of Slow or Floating CMOS Inputs, SCBA004

12.2 Related Links

The table below lists quick access links. Categories include technical documents, support and community resources, tools and software, and quick access to sample or buy.

Table 5. Related Links

PARTS	PRODUCT FOLDER	SAMPLE & BUY	TECHNICAL DOCUMENTS	TOOLS & SOFTWARE	SUPPORT & COMMUNITY
CD54HC4051	Click here	Click here	Click here	Click here	Click here
CD74HC4051	Click here	Click here	Click here	Click here	Click here
CD54HCT4051	Click here	Click here	Click here	Click here	Click here
CD74HCT4051	Click here	Click here	Click here	Click here	Click here
CD54HC4052	Click here	Click here	Click here	Click here	Click here
CD74HC4052	Click here	Click here	Click here	Click here	Click here
CD54HCT4052	Click here	Click here	Click here	Click here	Click here
CD74HCT4052	Click here	Click here	Click here	Click here	Click here
CD54HC4053	Click here	Click here	Click here	Click here	Click here
CD74HC4053	Click here	Click here	Click here	Click here	Click here
CD54HCT4053	Click here	Click here	Click here	Click here	Click here
CD74HCT4053	Click here	Click here	Click here	Click here	Click here

12.3 Receiving Notification of Documentation Updates

To receive notification of documentation updates, navigate to the device product folder on ti.com. In the upper right corner, click on Alert me to register and receive a weekly digest of any product information that has changed. For change details, review the revision history included in any revised document.

12.4 Community Resources

The following links connect to TI community resources. Linked contents are provided "AS IS" by the respective contributors. They do not constitute TI specifications and do not necessarily reflect TI's views; see TI's Terms of Use.

TI E2E™ Online Community T's Engineer-to-Engineer (E2E) Community. Created to foster collaboration among engineers. At e2e.ti.com, you can ask questions, share knowledge, explore ideas and help solve problems with fellow engineers.

Design Support TI's Design Support Quickly find helpful E2E forums along with design support tools and contact information for technical support.

12.5 Trademarks

E2E is a trademark of Texas Instruments.

All other trademarks are the property of their respective owners.

12.6 Electrostatic Discharge Caution



These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.





12.7 Glossary

SLYZ022 — TI Glossary.

This glossary lists and explains terms, acronyms, and definitions.

13 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.





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PACKAGING INFORMATION

Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
5962-8775401EA	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-8775401EA CD54HC4053F3A	Samples
5962-8855601EA	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-8855601EA CD54HC4052F3A	Samples
5962-9065401MEA	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-9065401ME A CD54HCT4051F3A	Samples
CD54HC4051F	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	CD54HC4051F	Samples
CD54HC4051F3A	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	CD54HC4051F3A	Samples
CD54HC4052F	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	CD54HC4052F	Samples
CD54HC4052F3A	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-8855601EA CD54HC4052F3A	Samples
CD54HC4053F	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	CD54HC4053F	Samples
CD54HC4053F3A	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-8775401EA CD54HC4053F3A	Samples
CD54HCT4051F3A	ACTIVE	CDIP	J	16	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-9065401ME A CD54HCT4051F3A	Samples
CD74HC4051E	ACTIVE	PDIP	N	16	25	RoHS & Green	NIPDAU	N / A for Pkg Type	-55 to 125	CD74HC4051E	Samples
CD74HC4051EE4	ACTIVE	PDIP	N	16	25	RoHS & Green	NIPDAU	N / A for Pkg Type	-55 to 125	CD74HC4051E	Samples
CD74HC4051M	ACTIVE	SOIC	D	16	40	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	HC4051M	Samples
CD74HC4051M96	ACTIVE	SOIC	D	16	2500	RoHS & Green	NIPDAU SN	Level-1-260C-UNLIM	-55 to 125	HC4051M	Samples
CD74HC4051M96E4	ACTIVE	SOIC	D	16	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	HC4051M	Samples
CD74HC4051M96G3	ACTIVE	SOIC	D	16	2500	RoHS & Green	SN	Level-1-260C-UNLIM	-55 to 125	HC4051M	Samples
CD74HC4051M96G4	ACTIVE	SOIC	D	16	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	HC4051M	Samples





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Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
CD74HC4051ME4	ACTIVE	SOIC	D	16	40	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	HC4051M	Samples
CD74HC4051MT	ACTIVE	SOIC	D	16	250	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	HC4051M	Samples
CD74HC4051NSR	ACTIVE	SO	NS	16	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	HC4051M	Samples
CD74HC4051NSRE4	ACTIVE	SO	NS	16	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	HC4051M	Samples
CD74HC4051PWR	ACTIVE	TSSOP	PW	16	2000	RoHS & Green	NIPDAU SN	Level-1-260C-UNLIM	-55 to 125	HJ4051	Samples
CD74HC4051PWRG4	ACTIVE	TSSOP	PW	16	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	HJ4051	Samples
CD74HC4051PWT	ACTIVE	TSSOP	PW	16	250	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	HJ4051	Samples
CD74HC4051PWTG4	ACTIVE	TSSOP	PW	16	250	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	HJ4051	Samples
CD74HC4052E	ACTIVE	PDIP	N	16	25	RoHS & Green	NIPDAU	N / A for Pkg Type	-55 to 125	CD74HC4052E	Samples
CD74HC4052M	ACTIVE	SOIC	D	16	40	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	HC4052M	Samples
CD74HC4052M96	ACTIVE	SOIC	D	16	2500	RoHS & Green	NIPDAU SN	Level-1-260C-UNLIM	-55 to 125	HC4052M	Samples
CD74HC4052M96E4	ACTIVE	SOIC	D	16	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	HC4052M	Samples
CD74HC4052M96G4	ACTIVE	SOIC	D	16	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	HC4052M	Samples
CD74HC4052MT	ACTIVE	SOIC	D	16	250	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	HC4052M	Samples
CD74HC4052NSR	ACTIVE	SO	NS	16	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	HC4052M	Samples
CD74HC4052PW	ACTIVE	TSSOP	PW	16	90	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	HJ4052	Samples
CD74HC4052PWR	ACTIVE	TSSOP	PW	16	2000	RoHS & Green	NIPDAU SN	Level-1-260C-UNLIM	-55 to 125	HJ4052	Samples
CD74HC4052PWRG4	ACTIVE	TSSOP	PW	16	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	HJ4052	Samples
CD74HC4052PWT	ACTIVE	TSSOP	PW	16	250	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	HJ4052	Samples
CD74HC4053E	ACTIVE	PDIP	N	16	25	RoHS & Green	NIPDAU	N / A for Pkg Type	-55 to 125	CD74HC4053E	Samples
CD74HC4053M	ACTIVE	SOIC	D	16	40	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	HC4053M	Samples





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Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
CD74HC4053M96	ACTIVE	SOIC	D	16	2500	RoHS & Green	NIPDAU SN	Level-1-260C-UNLIM	-55 to 125	HC4053M	Samples
CD74HC4053M96G3	ACTIVE	SOIC	D	16	2500	RoHS & Green	SN	Level-1-260C-UNLIM	-55 to 125	HC4053M	Samples
CD74HC4053M96G4	ACTIVE	SOIC	D	16	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	HC4053M	Samples
CD74HC4053ME4	ACTIVE	SOIC	D	16	40	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	HC4053M	Samples
CD74HC4053MG4	ACTIVE	SOIC	D	16	40	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	HC4053M	Samples
CD74HC4053MT	ACTIVE	SOIC	D	16	250	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	HC4053M	Samples
CD74HC4053NSR	ACTIVE	so	NS	16	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	HC4053M	Samples
CD74HC4053PW	ACTIVE	TSSOP	PW	16	90	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	HJ4053	Samples
CD74HC4053PWR	ACTIVE	TSSOP	PW	16	2000	RoHS & Green	NIPDAU SN	Level-1-260C-UNLIM	-55 to 125	HJ4053	Samples
CD74HC4053PWRG4	ACTIVE	TSSOP	PW	16	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	HJ4053	Samples
CD74HC4053PWT	ACTIVE	TSSOP	PW	16	250	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	HJ4053	Samples
CD74HCT4051E	ACTIVE	PDIP	N	16	25	RoHS & Green	NIPDAU	N / A for Pkg Type	-55 to 125	CD74HCT4051E	Samples
CD74HCT4051M	ACTIVE	SOIC	D	16	40	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	HCT4051M	Samples
CD74HCT4051M96	ACTIVE	SOIC	D	16	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	HCT4051M	Samples
CD74HCT4051M96E4	ACTIVE	SOIC	D	16	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	HCT4051M	Samples
CD74HCT4051M96G4	ACTIVE	SOIC	D	16	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	HCT4051M	Samples
CD74HCT4051ME4	ACTIVE	SOIC	D	16	40	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	HCT4051M	Samples
CD74HCT4051MG4	ACTIVE	SOIC	D	16	40	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	HCT4051M	Samples
CD74HCT4051MT	ACTIVE	SOIC	D	16	250	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	HCT4051M	Samples
CD74HCT4052E	ACTIVE	PDIP	N	16	25	RoHS & Green	NIPDAU	N / A for Pkg Type	-55 to 125	CD74HCT4052E	Samples
CD74HCT4052M	ACTIVE	SOIC	D	16	40	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	HCT4052M	Samples



PACKAGE OPTION ADDENDUM

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Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
CD74HCT4052M96	ACTIVE	SOIC	D	16	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	HCT4052M	Samples
CD74HCT4052M96G4	ACTIVE	SOIC	D	16	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	HCT4052M	Samples
CD74HCT4052MT	ACTIVE	SOIC	D	16	250	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	HCT4052M	Samples
CD74HCT4053E	ACTIVE	PDIP	N	16	25	RoHS & Green	NIPDAU	N / A for Pkg Type	-55 to 125	CD74HCT4053E	Samples
CD74HCT4053M	ACTIVE	SOIC	D	16	40	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	HCT4053M	Samples
CD74HCT4053M96	ACTIVE	SOIC	D	16	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	HCT4053M	Samples
CD74HCT4053M96E4	ACTIVE	SOIC	D	16	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	HCT4053M	Samples
CD74HCT4053M96G4	ACTIVE	SOIC	D	16	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	HCT4053M	Samples
CD74HCT4053ME4	ACTIVE	SOIC	D	16	40	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	HCT4053M	Samples
CD74HCT4053MT	ACTIVE	SOIC	D	16	250	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	HCT4053M	Samples
CD74HCT4053PWR	ACTIVE	TSSOP	PW	16	2000	RoHS & Green	NIPDAU SN	Level-1-260C-UNLIM	-55 to 125	HK4053	Samples
CD74HCT4053PWRE4	ACTIVE	TSSOP	PW	16	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	HK4053	Samples
CD74HCT4053PWRG4	ACTIVE	TSSOP	PW	16	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	HK4053	Samples
CD74HCT4053PWT	ACTIVE	TSSOP	PW	16	250	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	HK4053	Samples

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

⁽²⁾ RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

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- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead finish/Ball material Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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OTHER QUALIFIED VERSIONS OF CD54HC4051, CD54HC4052, CD54HC4053, CD54HC4051, CD74HC4051, CD74HC4052, CD74HC4053, CD74HC4051:

- Catalog: CD74HC4051, CD74HC4052, CD74HC4053, CD74HCT4051
- Automotive: CD74HC4051-Q1, CD74HCT4051-Q1, CD74HC4051-Q1, CD74HCT4051-Q1
- Enhanced Product: CD74HC4051-EP, CD74HC4051-EP
- Military: CD54HC4051, CD54HC4052, CD54HC4053, CD54HCT4051

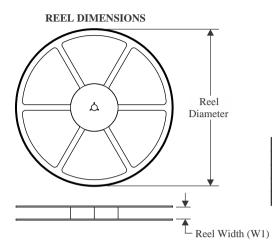
NOTE: Qualified Version Definitions:

- Catalog TI's standard catalog product
- Automotive Q100 devices qualified for high-reliability automotive applications targeting zero defects
- Enhanced Product Supports Defense, Aerospace and Medical Applications
- Military QML certified for Military and Defense Applications



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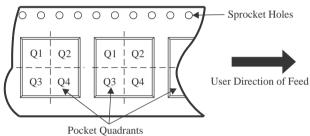
TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
CD74HC4051M96	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
CD74HC4051M96	SOIC	D	16	2500	330.0	16.8	6.5	10.3	2.1	8.0	16.0	Q1
CD74HC4051M96G3	SOIC	D	16	2500	330.0	16.8	6.5	10.3	2.1	8.0	16.0	Q1
CD74HC4051M96G4	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
CD74HC4051NSR	SO	NS	16	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
CD74HC4051PWR	TSSOP	PW	16	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
CD74HC4051PWR	TSSOP	PW	16	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
CD74HC4051PWRG4	TSSOP	PW	16	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
CD74HC4051PWT	TSSOP	PW	16	250	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
CD74HC4052M96	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
CD74HC4052M96	SOIC	D	16	2500	330.0	16.8	6.5	10.3	2.1	8.0	16.0	Q1
CD74HC4052M96G4	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
CD74HC4052NSR	SO	NS	16	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
CD74HC4052PWR	TSSOP	PW	16	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
CD74HC4052PWR	TSSOP	PW	16	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
CD74HC4052PWRG4	TSSOP	PW	16	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1



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Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
CD74HC4052PWT	TSSOP	PW	16	250	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
CD74HC4053M96	SOIC	D	16	2500	330.0	16.8	6.5	10.3	2.1	8.0	16.0	Q1
CD74HC4053M96	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
CD74HC4053M96G3	SOIC	D	16	2500	330.0	16.8	6.5	10.3	2.1	8.0	16.0	Q1
CD74HC4053M96G4	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
CD74HC4053NSR	SO	NS	16	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
CD74HC4053PWR	TSSOP	PW	16	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
CD74HC4053PWR	TSSOP	PW	16	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
CD74HC4053PWRG4	TSSOP	PW	16	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
CD74HC4053PWT	TSSOP	PW	16	250	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
CD74HCT4051M96	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
CD74HCT4052M96	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
CD74HCT4053M96	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
CD74HCT4053PWR	TSSOP	PW	16	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
CD74HCT4053PWR	TSSOP	PW	16	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
CD74HCT4053PWRG4	TSSOP	PW	16	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
CD74HCT4053PWT	TSSOP	PW	16	250	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1



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*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
CD74HC4051M96	SOIC	D	16	2500	340.5	336.1	32.0
CD74HC4051M96	SOIC	D	16	2500	364.0	364.0	27.0
CD74HC4051M96G3	SOIC	D	16	2500	364.0	364.0	27.0
CD74HC4051M96G4	SOIC	D	16	2500	340.5	336.1	32.0
CD74HC4051NSR	SO	NS	16	2000	367.0	367.0	38.0
CD74HC4051PWR	TSSOP	PW	16	2000	364.0	364.0	27.0
CD74HC4051PWR	TSSOP	PW	16	2000	356.0	356.0	35.0
CD74HC4051PWRG4	TSSOP	PW	16	2000	356.0	356.0	35.0
CD74HC4051PWT	TSSOP	PW	16	250	356.0	356.0	35.0
CD74HC4052M96	SOIC	D	16	2500	340.5	336.1	32.0
CD74HC4052M96	SOIC	D	16	2500	364.0	364.0	27.0
CD74HC4052M96G4	SOIC	D	16	2500	340.5	336.1	32.0
CD74HC4052NSR	SO	NS	16	2000	356.0	356.0	35.0
CD74HC4052PWR	TSSOP	PW	16	2000	364.0	364.0	27.0
CD74HC4052PWR	TSSOP	PW	16	2000	356.0	356.0	35.0
CD74HC4052PWRG4	TSSOP	PW	16	2000	356.0	356.0	35.0
CD74HC4052PWT	TSSOP	PW	16	250	356.0	356.0	35.0
CD74HC4053M96	SOIC	D	16	2500	364.0	364.0	27.0



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Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
CD74HC4053M96	SOIC	D	16	2500	340.5	336.1	32.0
CD74HC4053M96G3	SOIC	D	16	2500	364.0	364.0	27.0
CD74HC4053M96G4	SOIC	D	16	2500	340.5	336.1	32.0
CD74HC4053NSR	SO	NS	16	2000	356.0	356.0	35.0
CD74HC4053PWR	TSSOP	PW	16	2000	356.0	356.0	35.0
CD74HC4053PWR	TSSOP	PW	16	2000	364.0	364.0	27.0
CD74HC4053PWRG4	TSSOP	PW	16	2000	356.0	356.0	35.0
CD74HC4053PWT	TSSOP	PW	16	250	356.0	356.0	35.0
CD74HCT4051M96	SOIC	D	16	2500	340.5	336.1	32.0
CD74HCT4052M96	SOIC	D	16	2500	340.5	336.1	32.0
CD74HCT4053M96	SOIC	D	16	2500	340.5	336.1	32.0
CD74HCT4053PWR	TSSOP	PW	16	2000	364.0	364.0	27.0
CD74HCT4053PWR	TSSOP	PW	16	2000	356.0	356.0	35.0
CD74HCT4053PWRG4	TSSOP	PW	16	2000	356.0	356.0	35.0
CD74HCT4053PWT	TSSOP	PW	16	250	356.0	356.0	35.0



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TUBE



*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
CD74HC4051E	N	PDIP	16	25	506	13.97	11230	4.32
CD74HC4051E	N	PDIP	16	25	506	13.97	11230	4.32
CD74HC4051EE4	N	PDIP	16	25	506	13.97	11230	4.32
CD74HC4051EE4	N	PDIP	16	25	506	13.97	11230	4.32
CD74HC4051M	D	SOIC	16	40	507	8	3940	4.32
CD74HC4051ME4	D	SOIC	16	40	507	8	3940	4.32
CD74HC4052E	N	PDIP	16	25	506	13.97	11230	4.32
CD74HC4052E	N	PDIP	16	25	506	13.97	11230	4.32
CD74HC4052M	D	SOIC	16	40	507	8	3940	4.32
CD74HC4052PW	PW	TSSOP	16	90	530	10.2	3600	3.5
CD74HC4053E	N	PDIP	16	25	506	13.97	11230	4.32
CD74HC4053E	N	PDIP	16	25	506	13.97	11230	4.32
CD74HC4053M	D	SOIC	16	40	507	8	3940	4.32
CD74HC4053ME4	D	SOIC	16	40	507	8	3940	4.32
CD74HC4053MG4	D	SOIC	16	40	507	8	3940	4.32
CD74HC4053PW	PW	TSSOP	16	90	530	10.2	3600	3.5
CD74HCT4051E	N	PDIP	16	25	506	13.97	11230	4.32
CD74HCT4051E	N	PDIP	16	25	506	13.97	11230	4.32
CD74HCT4051M	D	SOIC	16	40	507	8	3940	4.32
CD74HCT4051ME4	D	SOIC	16	40	507	8	3940	4.32
CD74HCT4051MG4	D	SOIC	16	40	507	8	3940	4.32
CD74HCT4052E	N	PDIP	16	25	506	13.97	11230	4.32
CD74HCT4052E	N	PDIP	16	25	506	13.97	11230	4.32
CD74HCT4052M	D	SOIC	16	40	507	8	3940	4.32
CD74HCT4053E	N	PDIP	16	25	506	13.97	11230	4.32
CD74HCT4053E	N	PDIP	16	25	506	13.97	11230	4.32
CD74HCT4053M	D	SOIC	16	40	507	8	3940	4.32
CD74HCT4053ME4	D	SOIC	16	40	507	8	3940	4.32

14 LEADS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.





SOP



- 1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing
- per ASME Y14.5M.

 2. This drawing is subject to change without notice.

 3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm, per side.
- 4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm, per side.



SOF



NOTES: (continued)

- 5. Publication IPC-7351 may have alternate designs.
- 6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SOF



NOTES: (continued)

- 7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 8. Board assembly site may have different recommendations for stencil design.



D (R-PDS0-G16)

PLASTIC SMALL OUTLINE



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AC.



D (R-PDSO-G16)

PLASTIC SMALL OUTLINE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.





SMALL OUTLINE PACKAGE



- 1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.

 2. This drawing is subject to change without notice.

 3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not
- exceed 0.15 mm per side.
- 4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
- 5. Reference JEDEC registration MO-153.



SMALL OUTLINE PACKAGE



NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SMALL OUTLINE PACKAGE



NOTES: (continued)

- 8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 9. Board assembly site may have different recommendations for stencil design.



MECHANICAL DATA

NS (R-PDSO-G**)

14-PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



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